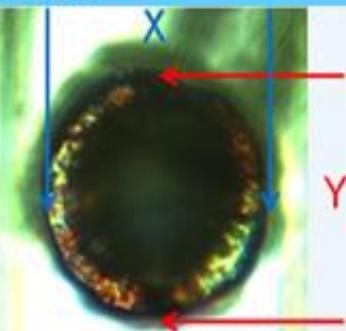
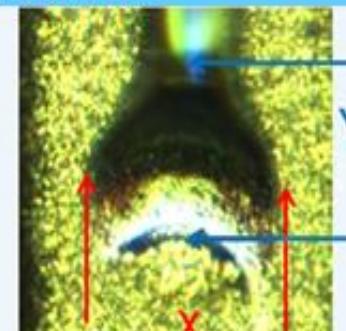
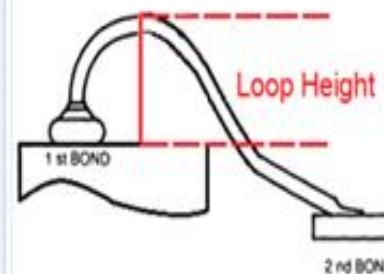
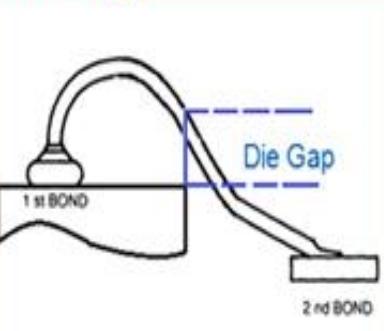
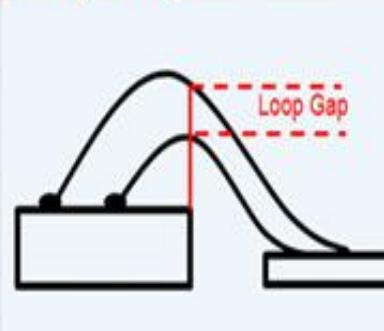
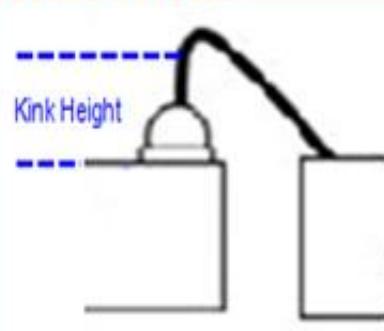


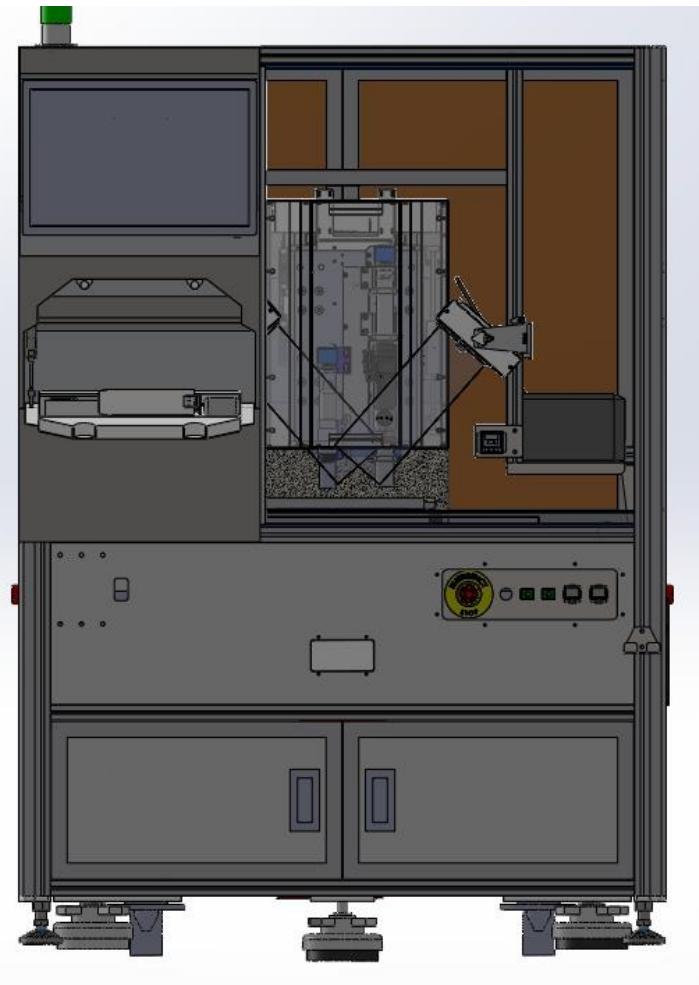
Outline

- Measurement items
- System layout
- Magnification change module
- Operation flow
- User interface
- Report example
- HL-620 General Specification

Measurement items

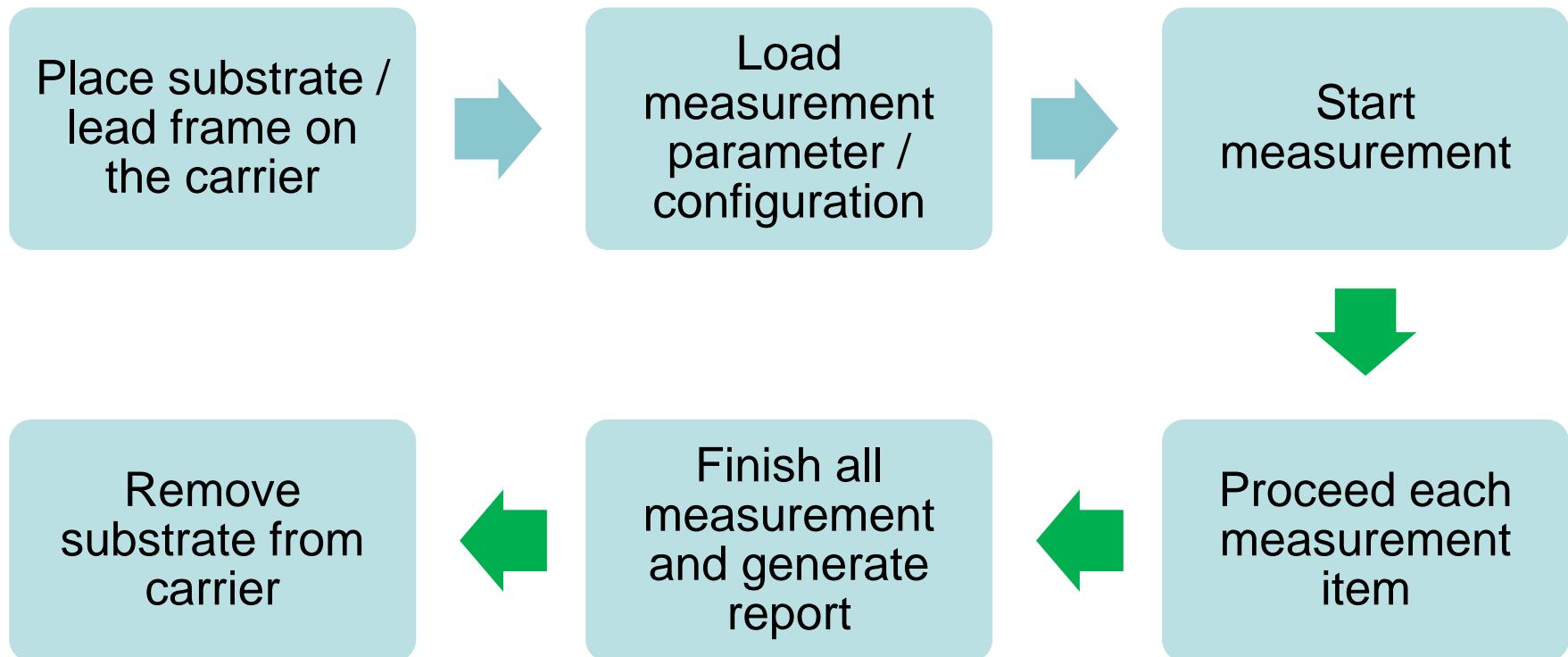
Ball X/Y 	Ball Thickness 	Stitch X/Y 	Loop Height 
Die Gap 	Loop Gap 	Kink Height 	The Highest Loop 

System layout



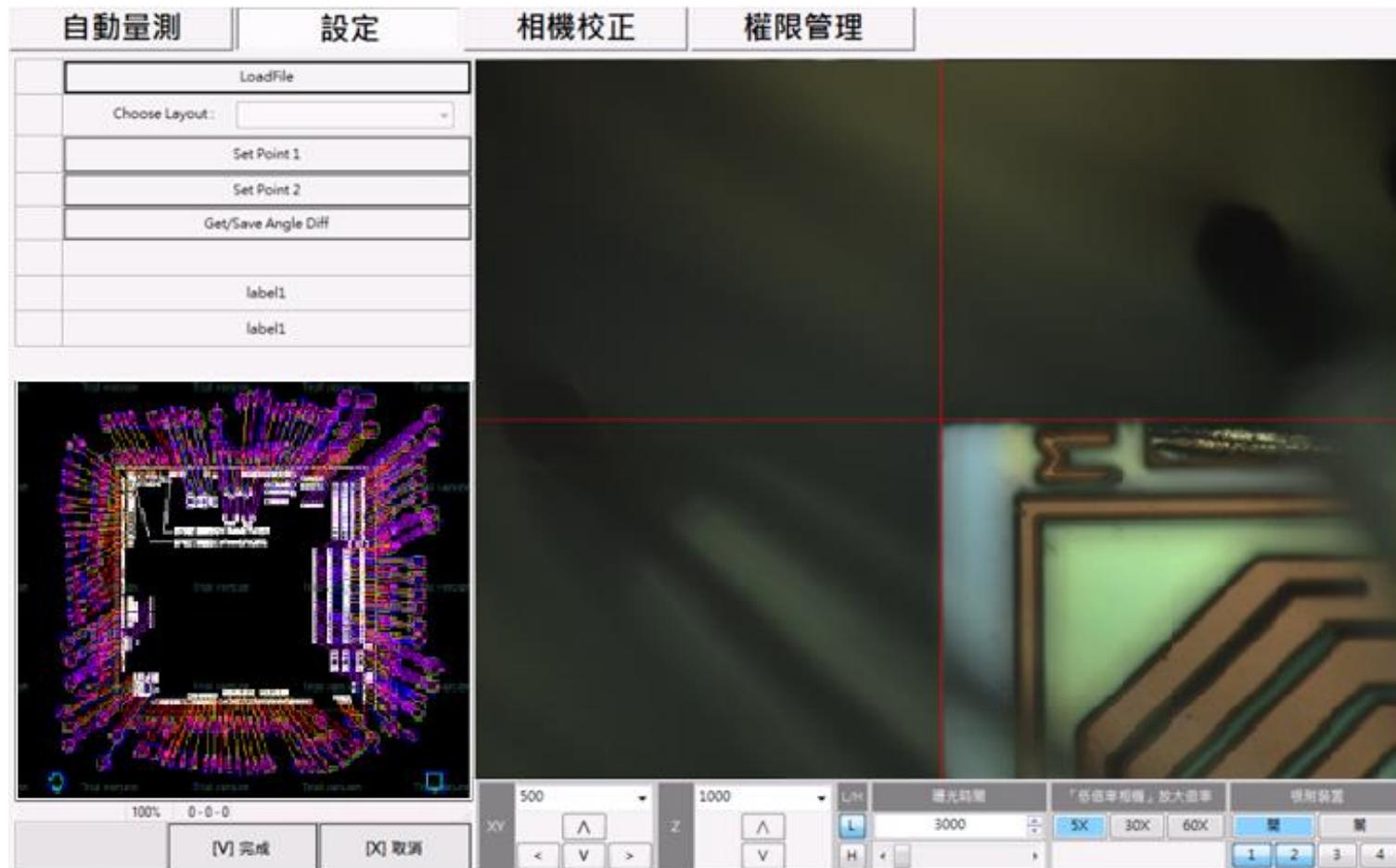
HI-LO SYSTEMS

Operation flow



User Interface

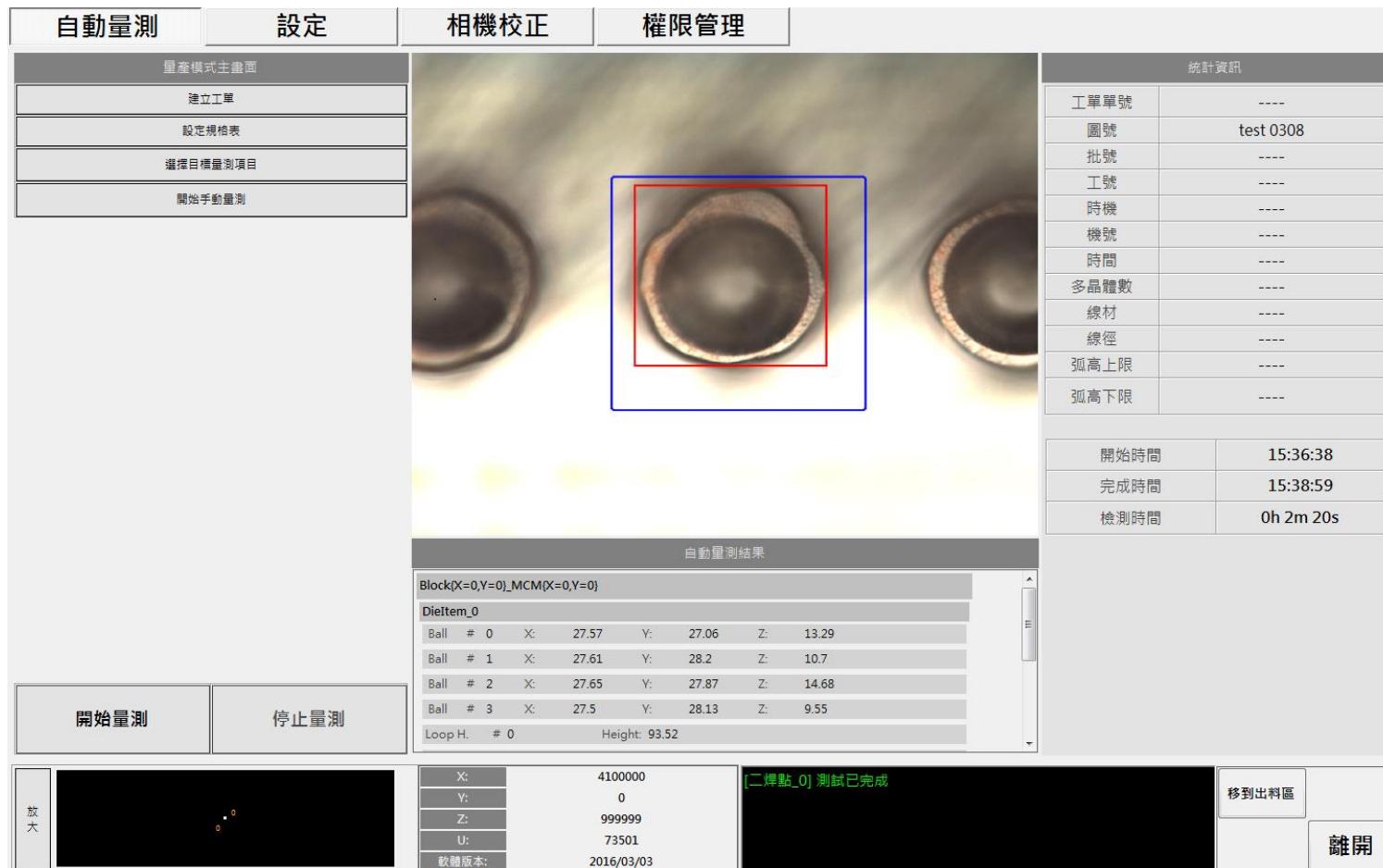
Program (Teach mode)



HI-LO SYSTEMS

User Interface

Auto measurement mode



Report example (.CSV)

批號	WB150129
工號	920135
時機	
機號	WB601
時間	20161020
多晶體數	
線材	C/W
線徑	1
弧高上限	
弧高下限	
Ball	59.63 58.86 59.6 62.02 60.07
BallY	59.63 59.71 60.44 60.7 60.9
BallZ	13.8 12.19 11.95 11.19 11.74
LoopHeight	305.1 340.12 361.22 277.84 280.46
LoopGap	60.25 67.77 68.25 69.24 68.47
DieGap	250.23 265.32 258.29 248.17 268.19
StitchX	51.91 53.35 51.84 58.97 51.43
StitchY	30.85 28.79 31.51 29.82 29.38
TheHighestLoop	308.03 342.99 359.98 255.94 306.03

HL-620 General Specification

Dimension	1120 * 1220* 1700 mm
Weight	1460 kg
Power requirement	220 VAC 60Hz 10A 1KW
Air consumption	0.6MPa, 55 l/min
Substrate / lead frame size	W : 25~80 mm L : 140~300 mm
Working platform / carrier	X/Y table working range: 400*140mm X/Y table resolution:± 0.1um Z axis resolution:± 0.01um Support lead frame / substrate
Measure	5M Camera , sensor size 1" 5X resolution:1 um / pixel 50X resolution:0.1 um / pixel 100X resolution:.005 um / pixel Ball(X/Y)/Stitch(X/Y) Measurement range:10~60um Ball(Z) Measurement range:1~800um Loop Height/Die Gap/Loop Gap/Kink Height/The Highest Loop Measurement range:1um ~ 5000um The Highest Loop search area:2500x2000um
Measure cycle time	Cu(1 Wire / Ball, Loop, Stitch):35 sec Au(1 Wire / Ball, Loop, Stitch):40 sec
Report format	TXT/XML/CSV
Communication interface	SECS/GEM (Optional)
User interface	Monitor, keyboard, barcode reader